

MAX solutions

Mill-Max Solder Preforms

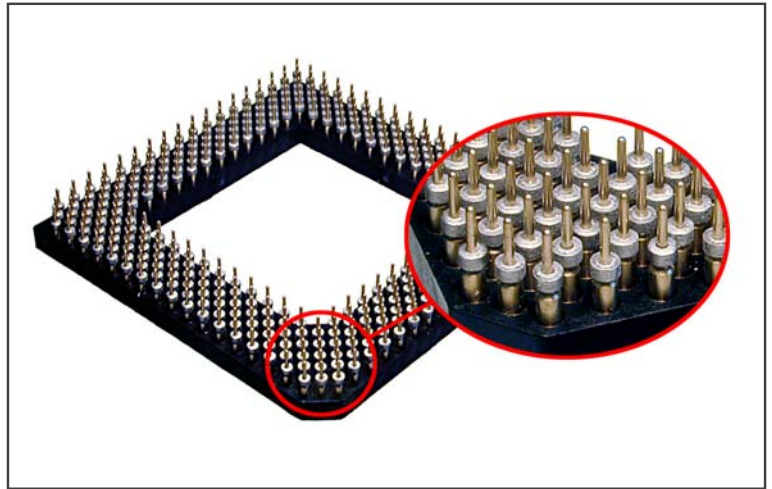
Mill-Max offers solder pre-forms. Solder preforms enhance the assembly of large pin grid array (PGA) sockets. The main benefit of solder preforms is the placement of solder directly between the lead and the hole. This ensures a good solder joint.

Solder preforms allow our customers to attach through-hole devices onto a board soldered using reflow methods. This allows for mixed technology boards.

The solder preform is 63% tin and 37% lead.

All Mill-Max sockets use precision-machined pins which eliminate any possibility of solder wicking or flux contamination. Press-fit into each pin receptacle is a low force beryllium copper multi-finger contact renowned for greater compliancy and proven reliability.

For additional information, please visit mill-max.com/PR489.



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